2SJ555

Silicon P Channel MOS FET High Speed Power Switching

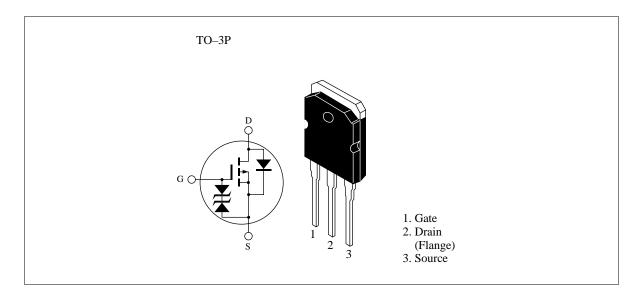
HITACHI

ADE-208-634A (Z) 2nd. Edition Jul. 1998

Features

- Low on-resistance $R_{DS(on)} = 0.017\Omega$ typ.
- Low drive current.
- 4V gate drive devices.
- High speed switching.

Outline





2SJ555

Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	-60	V	
Gate to source voltage	V _{GSS}	±20	V	
Drain current	I _D	-60	А	
Drain peak current	Note1 D(pulse)	-240	А	
Body-drain diode reverse drain current	I _{DR}	-60	А	
Avalanche current	I Note3	-60	А	
Avalanche energy	E _{AR} Note3	308	mJ	
Channel dissipation	Pch Note2	125	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

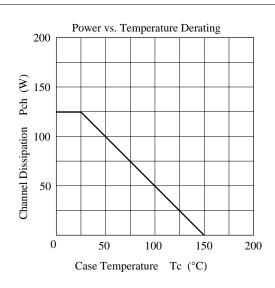
- Note: 1. PW \leq 10 μ s, duty cycle \leq 1 %
 - 2. Value at Tc = 25°C
 - 3. Value at Tch = 25°C, Rg \geq 50 Ω

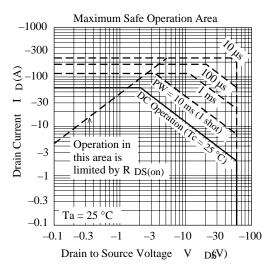
Electrical Characteristics ($Ta = 25^{\circ}C$)

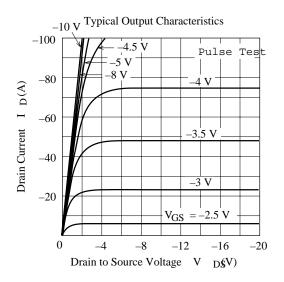
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-60	_	_	V	$I_{D} = -10 \text{mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \mu A, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	_	-10	μΑ	$V_{DS} = -60 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16V, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-1.0	_	-2.0	V	$I_{D} = -1 \text{mA}, V_{DS} = -10 \text{V}$
Static drain to source on state	R _{DS(on)}	_	0.017	0.022	Ω	$I_{\rm D} = -30$ A, $V_{\rm GS} = -10$ V Note4
resistance	R _{DS(on)}	_	0.024	0.036	Ω	$I_{\rm D} = -30 {\rm A}, \ V_{\rm GS} = -4 {\rm V}^{\rm Note4}$
Forward transfer admittance	y _{fs}	27	45	_	S	$I_D = -30A$, $V_{DS} = -10V^{Note4}$
Input capacitance	Ciss	_	4100	_	pF	$V_{DS} = -10V$
Output capacitance	Coss	_	2100	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	450	_	pF	f = 1MHz
Turn-on delay time	$t_{d(on)}$	_	32	_	ns	$V_{GS} = -10V, I_{D} = -30A$
Rise time	t _r	_	270	_	ns	$R_L = 1\Omega$
Turn-off delay time	t _{d(off)}	_	570	_	ns	_
Fall time	t _f	_	360	_	ns	_
Body-drain diode forward voltage	V_{DF}	_	-1.1	_	V	$I_F = -60A, V_{GS} = 0$
Body–drain diode reverse recovery time	t _{rr}		115		ns	$I_F = -60A, V_{GS} = 0$ diF/ dt =50A/ μ s

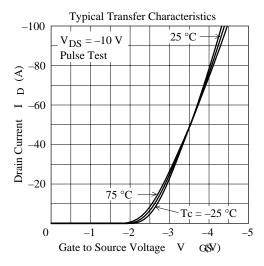
Note: 4. Pulse test

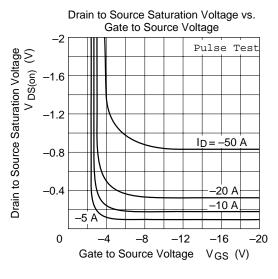
Main Characteristics

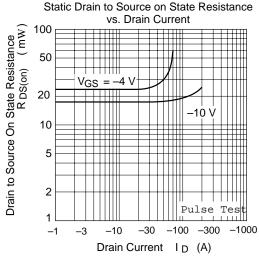


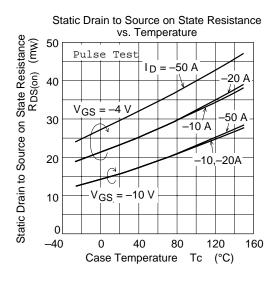


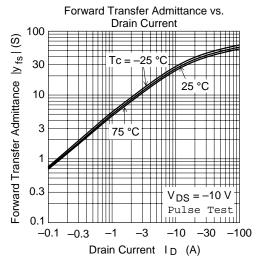


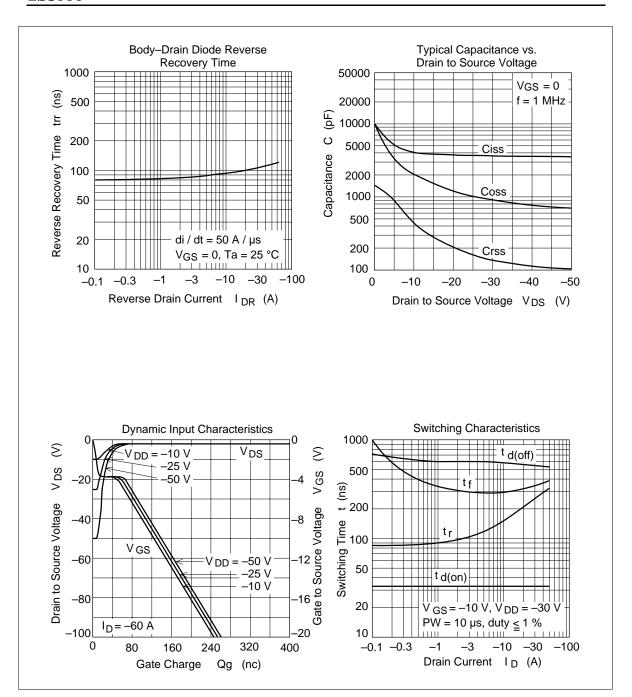


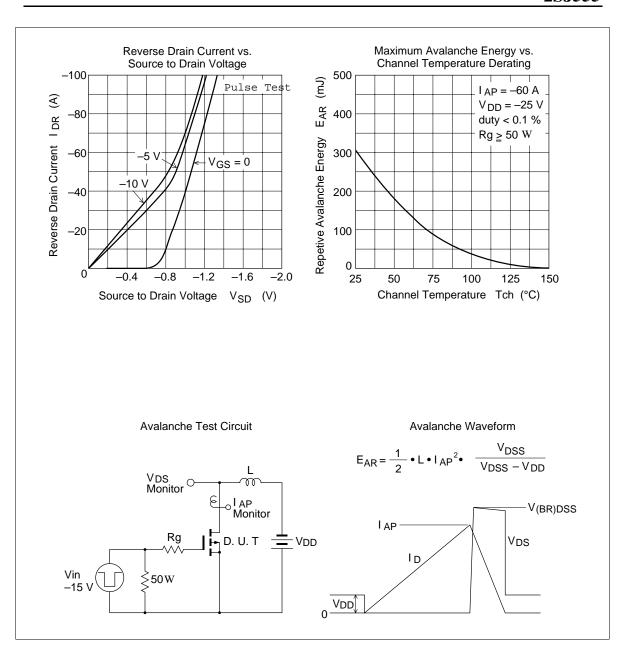


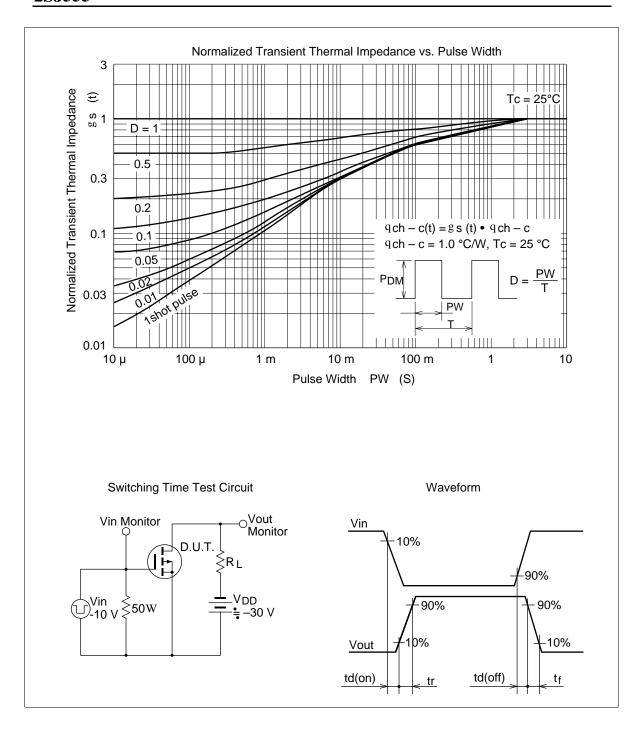




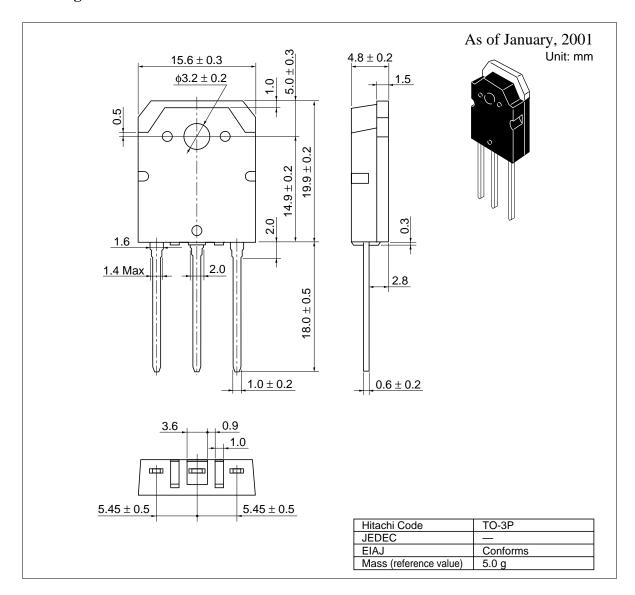








Package Dimensions



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